

POWER OF ATTORNEY; REVOCATION OF PREVIOUS **POWERS: AND** STATEMENT UNDER 37 CFR 3.73(b) Application

Application Number	09/974,721	
Títle	Method for Automatically De- Skewing of Multiple Layer Wafer for Improved Pattern Recognition	
Filing Date	October 9, 2001	
First Named Inventor	Jian Zhou	
Group Art Unit	1765	
Examiner Name	Unknown	
Attorney Docket No.	NAN050 US	

Nanometrics Incorporated having a place of business at 1550 Buckeye Drive, Milpitas, CA 95035-7418 states that to the best of its knowledge and belief it is the assignee or is entitled to ownership of the entire right, title, and interest in and to the above-referenced patent application by virtue of an Assignment recorded with the U.S. Patent and Trademark Office a copy of which is attached hereto and represents that the undersigned is a representative authorized and empowered to sign on behalf of Nanometrics Incorporated. See 37 C.F.R. 3.73(b).

Nanometrics Incorporated hereby revokes all powers of attorney previously given and appoints the attorneys identified by the following Customer Number with full power of substitution and revocation, to prosecute this application, and to transact all business in the U.S. Patent and Trademark Office in connection therewith. Please send all future correspondence to the attention of Michael J. Halbert (40,633) care of the address associated with the following customer number and please direct all telephone calls to the same.

Please change the Correspondence Address for the above-identified application to: GROUP TOO

Customer Number

34036 PATENT TRADEMARK OFFICE

Please also update the Attorney Docket Number to NAN050 US

SIGNATURE of Applicant or Assignee of Record

Signature:

Name:

Title:

President and CEO

Attorney Docket No.: M-11928 US

ASSIGNMENT

For good and valuable consideration, receipt of which is hereby acknowledged, we

Jian Zhou

of 3648 Bloomsbury Way, San Jose, California 95132

Hua Chu

of 18188 Kenyon Court, Saratoga, California 95070

hereby sell, assign and transfer to Nanometrics Incorporated, a California corporation, having a place of business at 1550 Buckeye Drive, Milpitas, California 95035-7418, its successors and assigns, the entire right, title and interest throughout the world in our invention in:

Method For Automatic De-Skewing Of Multiple Layer Wafer For Improved Pattern Recognition

for which we have filed a United States patent application on October 9, 2001, which now has Serial No. 09/974,721, and all patent applications and patents of every country for said invention, including divisions, reissues, continuations and extensions thereof, and all rights of priority resulting from the filing of said applications; we authorize the above-named assignee to apply for patents of foreign countries for said invention, and to claim all rights of priority without further authorization from us; we agree to execute all papers useful in connection with said United States and foreign applications, and generally to do everything possible to aid said assignee, its successors, assigns and nominees, at their request and expense, in obtaining and enforcing patents for said invention in all countries; and we request the Commissioner of Patents and Trademarks to issue all patents granted for said invention to the above-named assignee, its successors and assigns.

Executed this 6th day of November , 2001.
5736
Jian Zhou

State of <u>California</u>) s
County of Santa Clara

on <u>loth November</u> before me, <u>Sheli Thornsbern</u> <u>Notang Public</u> personally appeared Jian Zhou personally known to me or proved to me on the basis of satisfactory evidence to be the person whose name is subscribed to the within instrument and acknowledged to me that he executed the same in his authorized capacity, and that by his signature on the instrument the person, or the entity upon behalf of which the person acted, executed the instrument.

WITNESS my hand and official seal.

SHELI THORNSBERRY
Comm. 8 1164758
NOTARY PUBLIC-CALIFORNIA
Samle Clara County
My Comm. Expires bec. 7, 2001

Signature OF NOTARY

Attorney Docket No.: M-11928 US

Executed this Uth day of _	November	, 2001.	
Excenses duo _4_,_ · · · · · ·		C 2-2	
		Hua Chu	
_			

State of <u>Cali-Fornia</u>) ss County of <u>Santa Clara</u>)

On Manher 10, 2001 before me, Sala Thorresperry Votary Public personally appeared Hua Chu personally known to me or proved to me on the basis of satisfactory evidence to be the person whose name is subscribed to the within instrument and acknowledged to me that he executed the same in his authorized capacity, and that by his signature on the instrument the person, or the entity upon behalf of which the person acted, executed the instrument.

WITNESS my hand and official seal.

SHELI THORNSBERRY
Comm. # 1164758
NOTARY PUBLIC - CALIFORNIA
Santa Clare County
My Comm. Expires Dec. 7, 2001

The Mondeny Notary Public



ATTORNEY OCKET NO: M-11928 US

	U.S. DEPARTMENT OF COMMERCE	
RECORDATION FORM PATENT	COVER SHEET PATENT AND TRADEMARK OFFICE S ONLY	
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THE HONORABLE DIRECTOR OF THE UNITED STATES PATENT RIGINAL DOCUMENTS OR COPY THEREOF.	AND TRADEMARK OFFICE. PLEASE RECORD THE ATTACHED	
Name of conveying party(ies):	Name and address of receiving party(ies):	
(a) Jian Zhou	Name: Nanometrics Incorporated	
	Street Address: 1550 Buckeye Drive	
(b) Hua Chu	City: Milpitas CA 95035-7418	
dditional name(s) of conveying party(les) attached?	Country: U.S.A.	
Yes No		
Nature of Conveyance:	Name and address of receiving party(les):	
Assignment Merger	Name:	
Security Agreement Change of Name	Street Address:	
Section Adjusting	City: State: Zip:	
Other	Country:	
Execution Date: November 6, 2001	Additional name(s) & address(es) attached?	
	☐ Yes ⊠ No	
If this document is being filed together with a new application	s. Patent No.(5)	
A. Patent Application No.(s) - 09/974,721 Title: Method For Automatic De-Skewing Of Multiple Laye Wafer For Improved Pattern Recognition	B. Patent No.(s)	
Patent Application No.(s) - 09/974,721 Title: Method For Automatic De-Skewing Of Multiple Laye Wafer For Improved Pattern Recognition Additional in Name and address of party to whom correspondence	B. Patent No.(s)	
A. Patent Application No.(s) - 09/974,721 Title: Method For Automatic De-Skewing Of Multiple Laye Wafer For Improved Pattern Recognition Additional in Name and address of party to whom correspondence concerning document should be malled:	B. Patent No.(s)	
A. Patent Application No.(s) - 09/974,721 Title: Method For Automatic De-Skewing Of Multiple Laye Wafer For Improved Pattern Recognition Additional in Additional in State and address of party to whom correspondence concerning document should be malled: Name: Michael J. Halbert	B. Patent No.(s)	
A. Patent Application No.(s) - 09/974,721 Title: Method For Automatic De-Skewing Of Multiple Layer Wafer For Improved Pattern Recognition Additional in Name and address of party to whom correspondence concerning document should be malled: Name: Michael J. Halbert Internal Address: SKJERVEN MORRILL MacPHERSON LLP	B. Patent No.(s) umbers attached? Yes No 6. Total number of applications and patents involved: 1	
A. Patent Application No.(s) - 09/974,721 Title: Method For Automatic De-Skewing Of Multiple Laye Wafer For Improved Pattern Recognition Additional Information Additional Information Additional Information Additional Information Additional Information Infor	B. Patent No.(s)	
A. Patent Application No.(s) - 09/974,721 Title: Method For Automatic De-Skewing Of Multiple Laye Wafer For Improved Pattern Recognition Additional in 5. Name and address of party to whom correspondence concerning document should be malled: Name: Michael J. Halbert Internal Address: SKJERVEN MORRILL MacPHERSON LLP Street Address: 25 METRO DRIVE, SUITE 700	B. Patent No.(s) umbers attached? Yes No 6. Total number of applications and patents involved: 1 7. Total fee (37 CFR 3.41): \$40.00	
A. Patent Application No.(s) - 09/974,721 Title: Method For Automatic De-Skewing Of Multiple Laye Wafer For Improved Pattern Recognition Additional in Name and address of party to whom correspondence concerning document should be malled: Name: Michael J. Halbert Internal Address: SKJERVEN MORRILL MacPHERSON LLP Street Address: 25 METRO DRIVE, SUITE 700	B. Patent No.(s) umbers attached? Yes No 6. Total number of applications and patents involved: 7. Total fee (37 CFR 3.41): Authorized to be charged to Deposit Account 19-2386	
A. Patent Application No.(s) - 09/974,721 Title: Method For Automatic De-Skewing Of Multiple Layer Wafer For Improved Pattern Recognition Additional in 5. Name and address of party to whom correspondence concerning document should be malled: Name: Michael J. Halbert Internal Address: SKJERVEN MORRILL MacPHERSON LLP Street Address: 25 METRO DRIVE, SUITE 700 City SAN JOSE State CA Zip 95110	B. Patent No.(s) umbers attached? Yes No 6. Total number of applications and patents involved: 1 7. Total fee (37 CFR 3.41): \$40.00 Authorized to be charged to Deposit Account 19-2386 Charge Deposit Account 19-2386 for any additional fer required for this conveyance and credit deposit account	
A. Patent Application No.(s) - 09/974,721 Title: Method For Automatic De-Skewing Of Multiple Layer Wafer For Improved Pattern Recognition Additional in 5. Name and address of party to whom correspondence concerning document should be malled: Name: Michael J. Halbert Internal Address: SKJERVEN MORRILL MacPHERSON LLP Street Address: 25 METRO DRIVE, SUITE 700 City SAN JOSE State CA Zip 95110	B. Patent No.(s) umbers attached? Yes No 6. Total number of applications and patents involved: 7. Total fee (37 CFR 3.41): Authorized to be charged to Deposit Account 19-2386 Charge Deposit Account 19-2386 for any additional fe required for this conveyance and credit deposit account 19-2386 any amounts overpaid	
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5 (excluding this cover sheet)	

Applicant(s):	Jian Zhou; Hua Chu;		
Assignee:	Nanometrics Incorporated		
Title:	Method for Automatically De-Skewing of Multiple Layer Wafer for Improved Pattern Recognition		
Serial No.:	09/974,721	Filing Date:	October 9, 2001
Examiner:	Unknown	Group Art Unit:	1765

Enclosed for filing in the U.S. Patent and Trademark Office for the above-identified application are the following:

Power of Attorney; Revocation of Previous Powers; and 1. Statement under 37 CFR 3.73(b) (1 page);

Copy of Assignment and Recordation Cover Sheet (3 pages) 2. and

Status Inquiry (1 page) 3.

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